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(54) **Title:** POWER MODULE PACKAGE WITH MOLDED VIA AND DUAL SIDE PRESS-FIT PIN

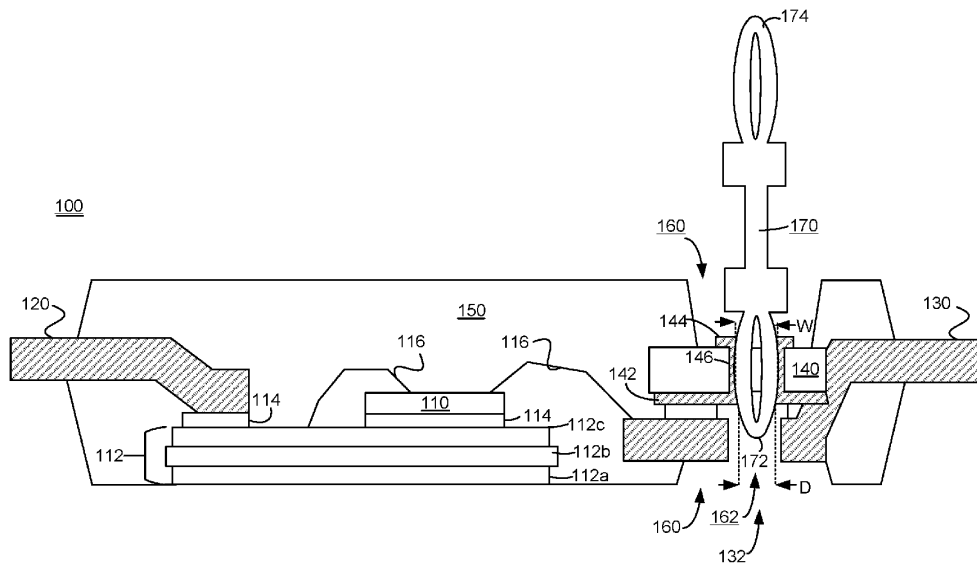


FIG. 1C

(57) **Abstract:** A module includes an assembly of a semiconductor device die (110), a lead frame (120, 130) connected to the semiconductor device die, and a substrate (112) connected to the lead frame. The substrate includes at least one plated-through hole (PTH) (162). A mold body (150) encapsulates the assembly. The mold body includes a through-mold via (TMV) (160) aligned with a portion of the substrate including the at least one PTH. The PTH is exposed in the TMV to an environment outside the mold body and is physically accessible from outside the mold body through the TMV.

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